

UNITED STATES PATENT AND TRADEMARK OFFICE



UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/462,796	01/13/2000	TAKAYOSHI WATANABE	500.38090X00	5528
7590 11/16/2004			EXAMINER	
ANTONELLI TERRY STOUT & KRAUS 1300 NORTH SEVENTEENTH STREET			NGUYEN, THANH T	
SUITE 1800			ART UNIT	PAPER NUMBER
ARLINGTON, VA 22209			2813	

DATE MAILED: 11/16/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
Office Action Summan	09/462,796	WATANABE ET AL.				
Office Action Summary	Examiner	Art Unit				
	Thanh T. Nguyen	2813				
The MAILING DATE of this communication ap Period for Reply	ppears on the cover sheet wi	th the correspondence address				
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a replication of the provision of the period for reply specified above, the maximum statutory period. - Failure to reply within the set or extended period for reply will, by statuted any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a r ply within the statutory minimum of third I will apply and will expire SIX (6) MON te, cause the application to become AB	eply be timely filed y (30) days will be considered timely. THS from the mailing date of this communication. ANDONED (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 9/13	Responsive to communication(s) filed on <u>9/13/04</u> .					
2a) This action is FINAL . 2b) ☑ Thi	This action is FINAL . 2b)⊠ This action is non-final.					
3) Since this application is in condition for allows	3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
closed in accordance with the practice under	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4) Claim(s) 34-53 is/are pending in the application	○ Claim(s) <u>34-53</u> is/are pending in the application.					
4a) Of the above claim(s) is/are withdra	4a) Of the above claim(s) is/are withdrawn from consideration.					
5)⊠ Claim(s) <u>53</u> is/are allowed.						
6)⊠ Claim(s) <u>34-52</u> is/are rejected.						
	Claim(s) is/are objected to.					
8) Claim(s) are subject to restriction and/	or election requirement.					
Application Papers		: : :				
9)☐ The specification is objected to by the Examir	ner.	•				
0)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.						
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO 152.						
11) I he oath or declaration is objected to by the E	xaminer. Note the aπacheo	Office Action or form PTO-152.				
Priority under 35 U.S.C. § 119						
 12) Acknowledgment is made of a claim for foreig a) All b) Some * c) None of: 1. Certified copies of the priority documer 2. Certified copies of the priority documer 3. Copies of the certified copies of the pri 	nts have been received. nts have been received in A	pplication No				
application from the International Bure	au (PCT Rule 17.2(a)).	:				
* See the attached detailed Office action for a list of the certified copies not received.						
Attachment(s)						
1) Notice of References Cited (PTO-892)		Summary (PTO-413) s)/Mail Date				
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) 		nformal Patent Application (PTO-152)				
Paper No(s)/Mail Date	6) Other:	<u></u> ·				

Application/Control Number: 09/462,796

Art Unit: 2813

DETAILED ACTION

Request for Continued Examination

The request filed on 9/13/04 for a Request for Continued Examination (RCE) under 37 CFR 1.114 is acceptable and a RCE has been established. An action on the RCE follows.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 34-52 are stand rejected under 35 U.S.C. 103(a) as being unpatentable over Yamaguchi et al. (U.S. Patent No. 6,271,110) in view of Akira (JP Patent No. 05-121409), Ochiai et al. (U.S. Patent No. 5,643,831) and Michihiko et al. (JP Patent No. 05206221) as previously applied.

Referring to figures 2a-2b, Yamaguchi et al. teaches a method of producing a semiconductor device comprising the steps of:

Forming a plurality of pyramidal bump electrodes (34) or the semiconductor device, and Connecting the pyramidal bump electrodes (34) to pad electrodes (32) of the semiconductor device,

Application/Control Number: 09/462,796

Art Unit: 2813

The step of forming the plurality of pyramidal bump electrodes including: a step of forming etched holes (14, called cavities, see figure 2a, col. 6, lines 60-67) by anisotropically etching base material having a crystal orientation (see col. 8, lines 37-42), and

A step of filling up the etched holes by plating a metal (see col. 9, lines 17-20) to form the pyramidal bump electrode (see figure 2B) by transferring a shape of the etched hole.

However, the reference does not teach etching a first oxidized film on the base material, removing the first oxidized film and forming a second oxidized film on the etched holes, forming a primary film of the same material as the metal for plating of the metal on the base material, and filling the metal such as gold/nickel, copper.

Akira teaches filling the opening with a copper or gold (20/26, see paragraph 21) by electroless plating.

Therefore, it would have been obvious to a person of ordinary skill in the requisite art at the time of the invention was made would fill the opening with a copper or gold by electroless plating in process of Yamaguchi et al. as taught by Akira because the process would provide excellent selectivity and adhesive strength on the film.

Ochiai et al. teaches a method of etching a first oxidized film on the base material, removing the first oxidized film and forming a second oxidized film on the etched holes (see figures 8A-8H and related text).

Therefore, it would have been obvious to a person of ordinary skill in the requisite art at the time of the invention was made would etch a first oxidized film on the base material, removing the first oxidized film and forming a second oxidized film on the etched holes in process of Yamaguchi et al. as taught by Ochiai et al. because the process would bring the plate

Art Unit: 2813

into a chemically stable condition and provides a low wetability to the plate, so a durability of the plate is improve and formed solder balls can be easily transferred.

Michihiko teaches forming a primary film of the same material as the metal for plating of the metal on the base material (see page 3, paragraph#7, meeting claim 35).

Therefore, it would have been obvious to a person of ordinary skill in the requisite art at the time of the invention was made would form a primary film of the same material as the metal for plating of the metal on the base material in process or Yamaguchi et al. as taught by Michihiko because the process would prevent generation of short-circuit.

It is known in the art to form the filling metal such as gold/nickel, copper.

Therefore, it would have been obvious to a person of ordinary skill in the requisite art at the time of the invention was made would form the filling metal such as gold/nickel, copper in process of Yamaguchi et al. because process in known in the art since determining the optimum material for the layer only involved routine skill in the art.

Allowable Subject Matter

Claim 53 is allowable over the prior art.

Response to Arguments

Applicant's arguments filed on 1/6/04 have been fully considered but they are not persuasive.

Applicant contends that Yamaguchi et al. does not disclose or suggest to form the bump shape by transferring the anisotropic etch hole. In response to applicant that Yamaguchi et al. clearly teaches form the bump shape by transferring the anisotropic etch hole (see figure 2B).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thanh Nguyen whose telephone number is (571) 272-1695, or by Email via address Thanh.Nguyen@uspto.gov. The examiner can normally be reached on Monday-Thursday from 6:00AM to 3:30PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead, Jr., can be reached on (571) 272-1702. The fax phone number for this Group is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Group receptionist whose telephone number is (703) 308-0956 (See MPEP 203.08).

Thanh Nguyen
Patent Examiner
Patent Examining Group 2800